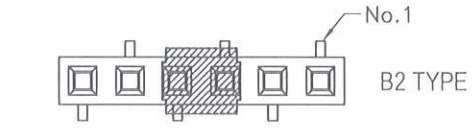
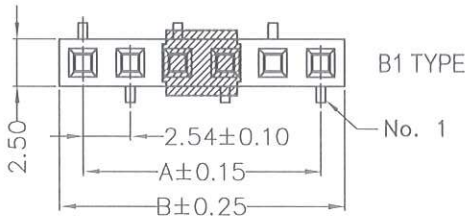
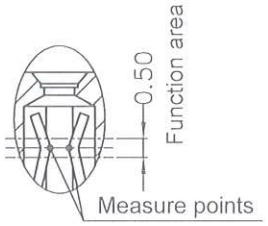
No. of Contacts	DIMENSIONS	
	A	B
2	2.54	5.24
3	5.08	7.78
4	7.62	10.32
5	10.16	12.86
6	12.70	15.40
7	15.24	17.94
8	17.78	20.48
9	20.32	23.02
10	22.86	25.56
11	25.40	28.10
12	27.94	30.64
13	30.48	33.18
14	33.02	35.72
15	35.56	38.26
16	38.10	40.80
17	40.64	43.34
18	43.18	45.88
19	45.72	48.42
20	48.26	50.96
21	50.80	53.50
22	53.34	56.04
23	55.88	58.58
24	58.42	61.12
25	60.96	63.66
26	63.50	66.20
27	66.04	68.74
28	68.58	71.28
29	71.12	73.82
30	73.66	76.36
31	76.20	78.90
32	78.74	81.44
33	81.28	83.98
34	83.82	86.52
35	86.36	89.06
36	88.90	91.60
37	91.44	94.14
38	93.98	96.68
39	96.52	99.22
40	99.06	101.76

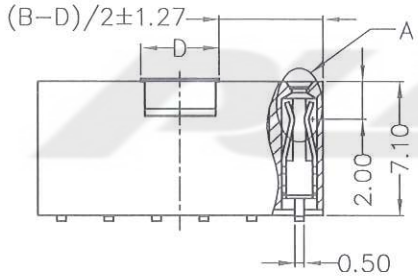


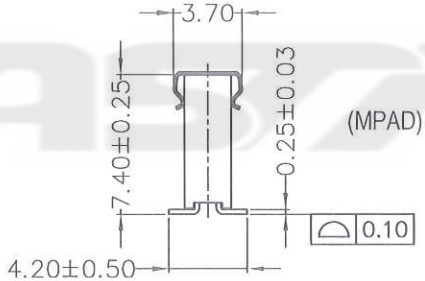


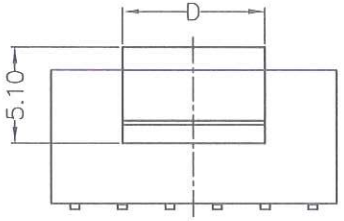


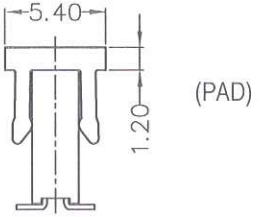
DETAIL A

SCALE 2:1









版次	ECN 编码	描述		设计/日期
		改前	改后	
7	CW09100018	/	变更版本发行	林秋兰_2001/03/22
8	EW18070007	/	更新MPAD0014规格	刘恋_2018/07/20

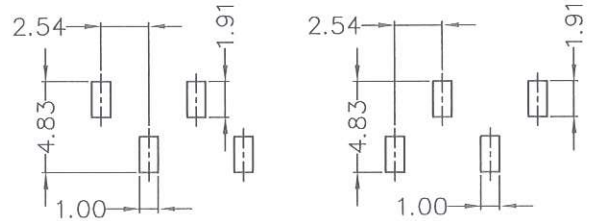
NOTES: (Unless otherwise specified)

1. Dimension shall be interpreted per ANSI Y14.5M.
2. Materials:
   Insulator material: High Temperature Thermoplastic, UL 94V-0;Color:Natural.
   Contact material: Copper Alloy.
3. Current Rating:3A Per Pin.
4. Voltage Rating: 30V AC/DC.
5. Working Temperature: -40℃ ~ +105℃.
6. Harmful material should be compliant to doc. "EI-0005" standards.
7. Product number matrix:

SPGFY - XXBX - X - *

- Number of Contacts
- B1: B1 TYPE; B2: B2 TYPE
- Contact Plating
- NULL:TRAY(W/0 MPAD,PAD); B : MPAD+REEL; E : MPAD+TUBE; P:PAD+TUBE; R:PAD+REEL; K:REEL(W/0 MPAD,PAD); G:TUBE

Definition			
Tin plated:			A
Gold plated:			
flash	B	15u"	F
10u"	E	30u"	J
Duplex plating			
flash	K	15u"	P
10u"	N	30u"	U
Standard: B All plating is lead free			



RECOMMEND PCB LAYOUT

TOLERANCE TABLE	
X. ± 0.30	X.° ± 3°
.X ± 0.25	.X° ± 2°
.XX ± 0.20	

SCALE	2.5:1	DRAWN	刘恋	DATE	2018/07/20
UNIT	mm	CHECK		DATE	2018/07/31
SIZE	A4	APPROVE		DATE	2018/07/31

DWG. NO.	600-0000-0713	TITLE	CUSTOMER DRAWING
PARTS NO.(INTENDED USE)	SPGFY-XXBX-X-*	REV.	8
		SHEET	1/1